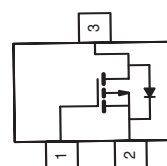
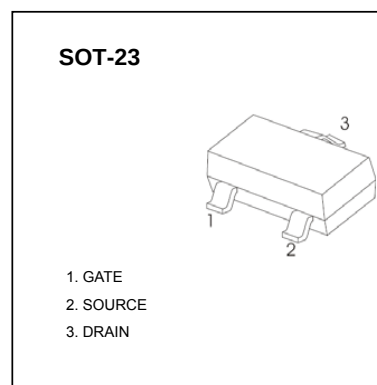


MOSFET PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (m Ω)	I_D (A) ^a	Q_g (Typ.)
- 12	35 at $V_{GS} = - 4.5$ V	- 5.1	9 nC
	45 at $V_{GS} = - 2.5$ V	- 4.5	
	59 at $V_{GS} = - 1.8$ V	- 3.9	

APPLICATIONS

- Load Switch
- PA Switch



ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	- 12	V
Gate-Source Voltage	V_{GS}	± 8	
Continuous Drain Current ($T_J = 150$ °C)	$T_C = 25$ °C	- 7.1	A
	$T_C = 70$ °C	- 5.7	
	$T_A = 25$ °C	- 5.1 ^{b, c}	
	$T_A = 70$ °C	- 4.0 ^{b, c}	
Pulsed Drain Current	I_{DM}	- 20	A
Continuous Source-Drain Diode Current	$T_C = 25$ °C	- 1.0	
	$T_A = 25$ °C	- 0.63 ^{b, c}	
Maximum Power Dissipation	$T_C = 25$ °C	2.5	W
	$T_C = 70$ °C	1.6	
	$T_A = 25$ °C	1.25 ^{b, c}	
	$T_A = 70$ °C	0.8 ^{b, c}	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	R_{thJA}	75	100	°C/W
Maximum Junction-to-Foot (Drain)	R_{thJF}	40	50	

Notes:

a. Based on $T_C = 25$ °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. $t = 5$ s.

d. Maximum under Steady State conditions is 166 °C/W.

MOSFET SPECIFICATIONS $T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted

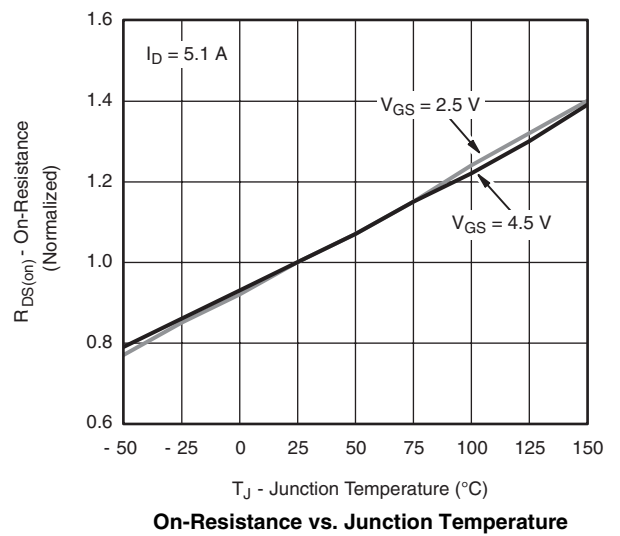
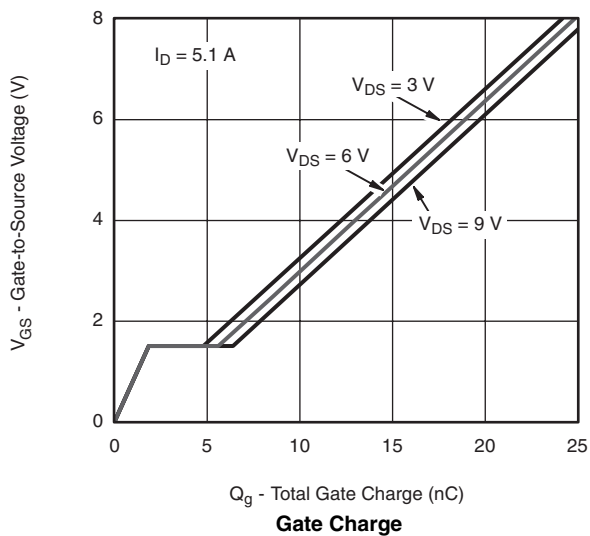
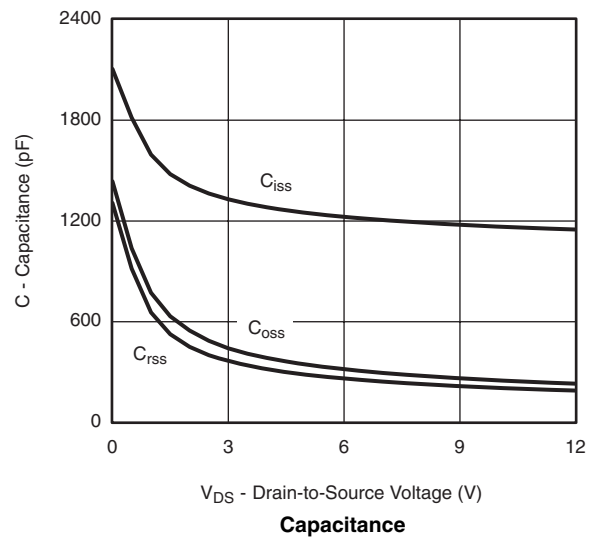
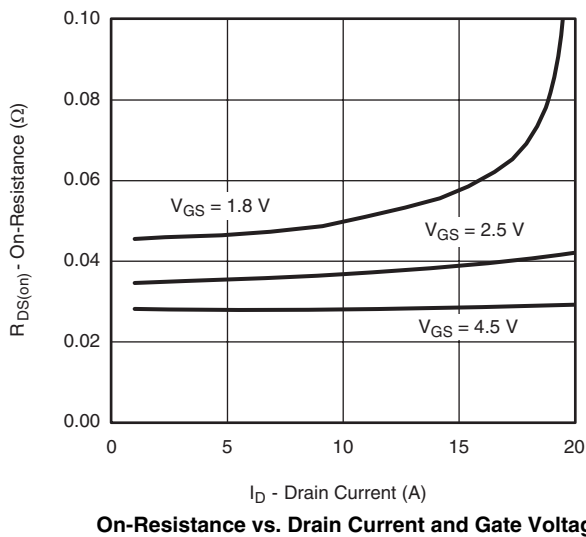
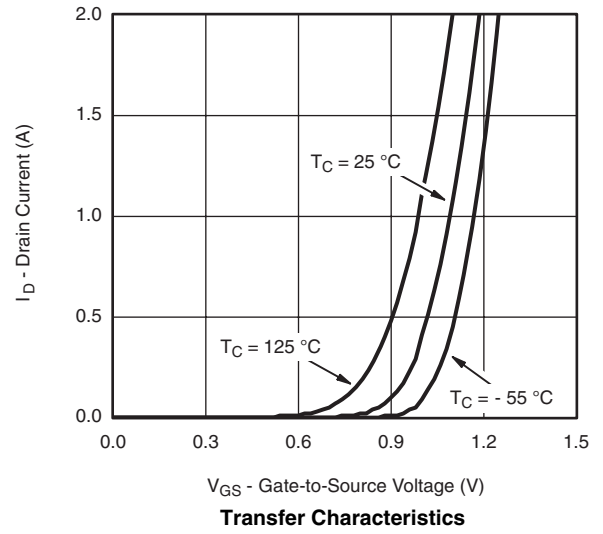
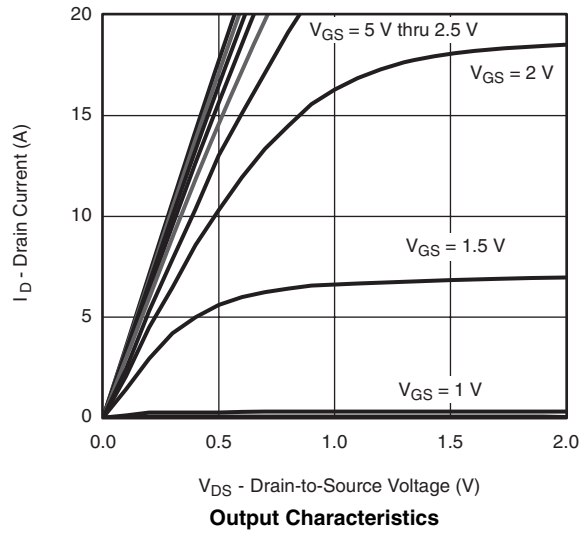
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{DS} = 0 V, I _D = - 250 μA	- 12			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = - 250 μA		- 13		mV/°C
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			2.6		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 0.4		- 1	V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 8 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 12 V, V _{GS} = 0 V			- 1	μA
		V _{DS} = - 12 V, V _{GS} = 0 V, T _J = 55 °C			- 10	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≤ - 5 V, V _{GS} = - 4.5 V	- 20			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 5.1 A		28.5	35	mΩ
		V _{GS} = - 2.5 V, I _D = - 4.5 A		36	45	
		V _{GS} = - 1.8 V, I _D = - 2.0 A		46	59	
Forward Transconductance ^a	g _{fs}	V _{DS} = - 5 V, I _D = - 5.3 A		18.5		S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{DS} = - 6 V, V _{GS} = 0 V, f = 1 MHz		1225		pF
Output Capacitance	C _{oss}			315		
Reverse Transfer Capacitance	C _{rss}			260		
Total Gate Charge	Q _g	V _{DS} = - 6 V, V _{GS} = - 4.5 V, I _D = - 5.1 A		15	25	nC
		V _{DS} = - 6 V, V _{GS} = - 2.5 V, I _D = - 5.1 A		9	15	
Gate-Source Charge	Q _{gs}			1.9		
Gate-Drain Charge	Q _{gd}			3.8		
Gate Resistance	R _g	f = 1 MHz		4.0		Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 6 V, R _L = 6 Ω I _D = - 1 A, V _{GEN} = - 4.5 V, R _G = 1 Ω		13	20	ns
Rise Time	t _r			35	60	
Turn-Off Delay Time	t _{d(off)}			45	70	
Fall Time	t _f			12	20	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 1.0	A
Pulse Diode Forward Current ^a	I _{SM}				- 20	
Body Diode Voltage	V _{SD}	I _S = - 1.0 A		- 0.7	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = - 1.0 A, dI/dt = 100 A/μs, T _J = 25 °C		32	50	ns
Body Diode Reverse Recovery Charge	Q _{rr}			20	40	nC
Reverse Recovery Fall Time	t _a			16		ns
Reverse Recovery Rise Time	t _b			16		

Notes:

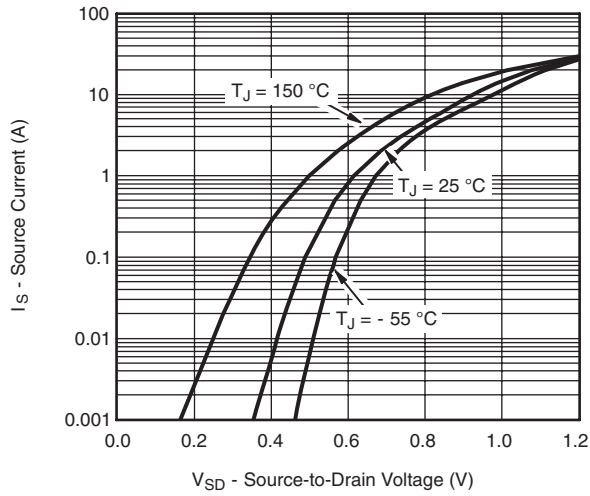
 a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

b. Guaranteed by design, not subject to production testing.

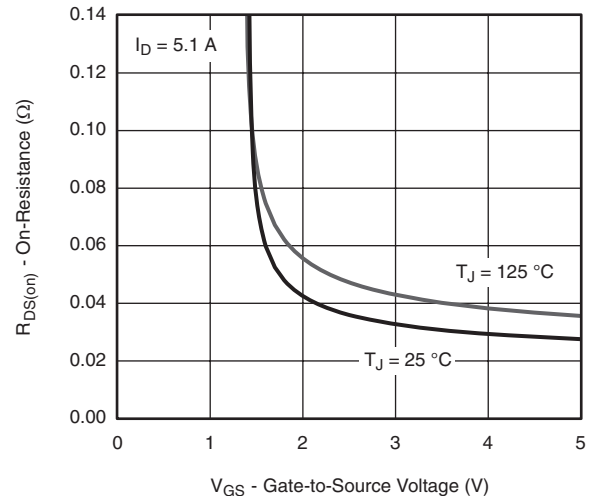
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



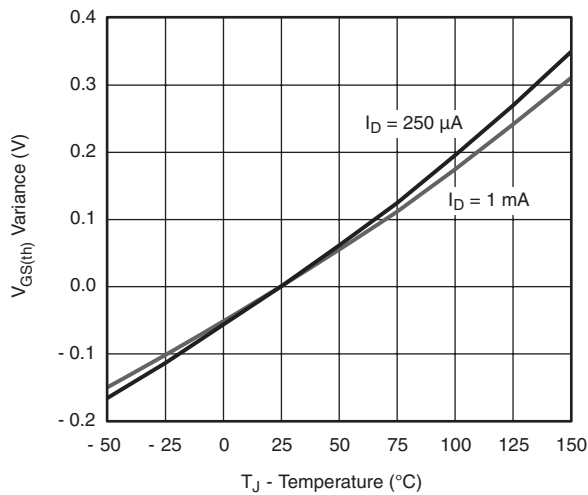
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



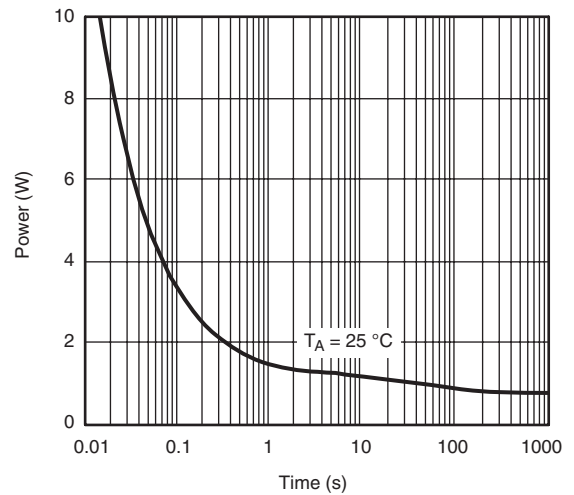
Source-Drain Diode Forward Voltage



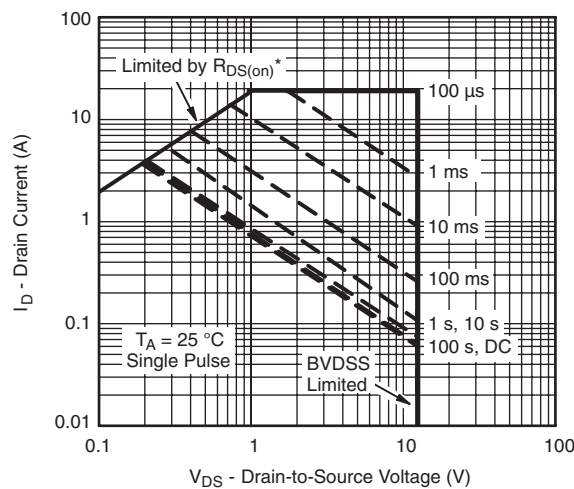
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



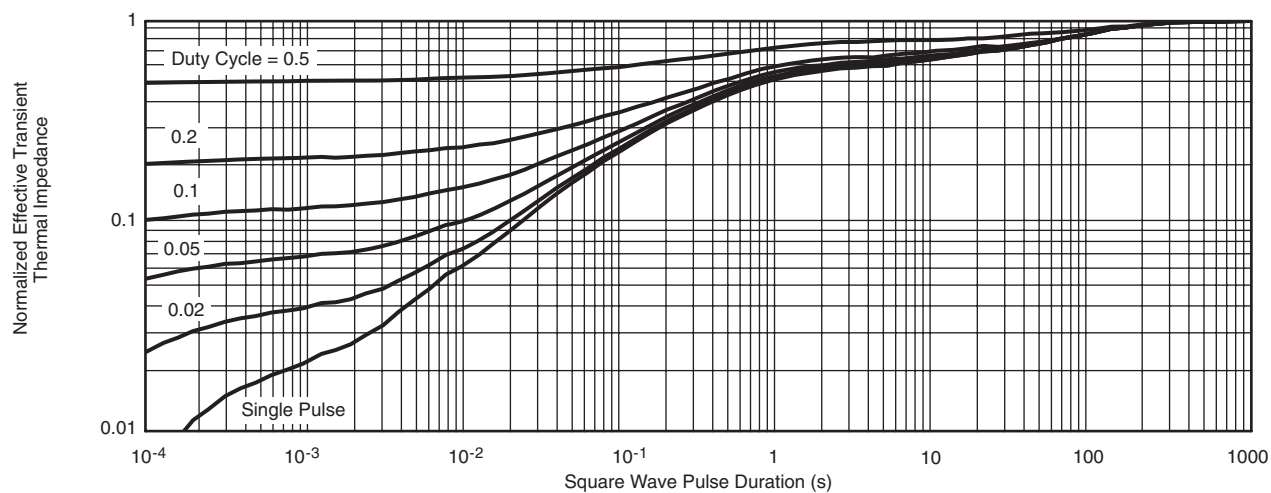
Single Pulse Power



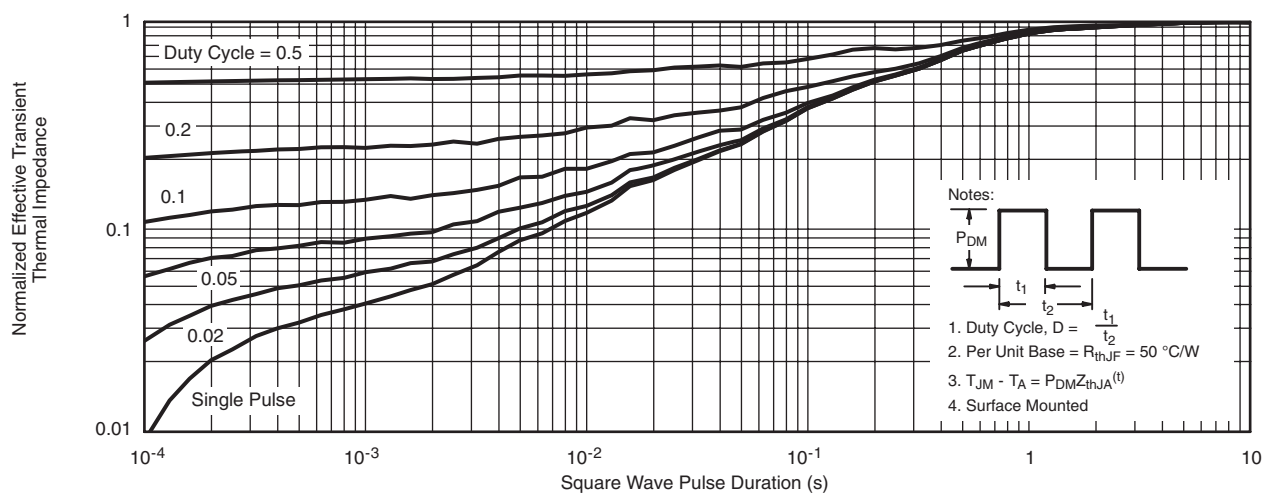
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

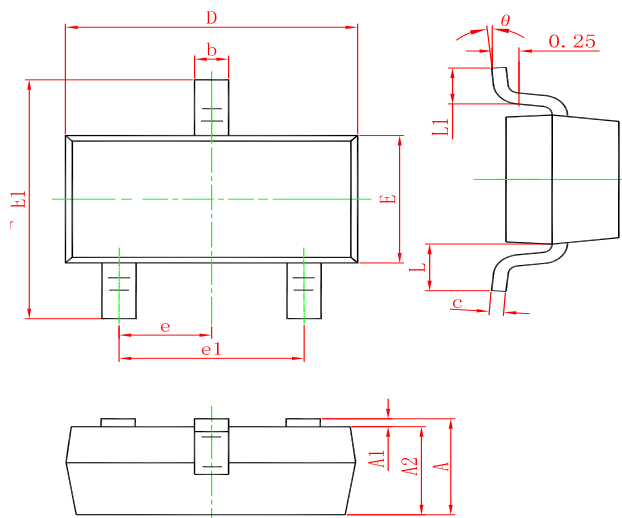


Normalized Thermal Transient Impedance, Junction-to-Ambient



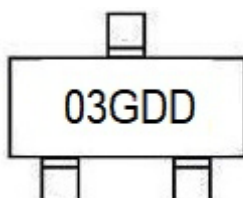
Normalized Thermal Transient Impedance, Junction-to-Foot

SOT-23 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Marking



Ordering information

Order code	Package	Baseqty	Deliverymode
SI2333CDS	SOT-23	3000	Tape and reel